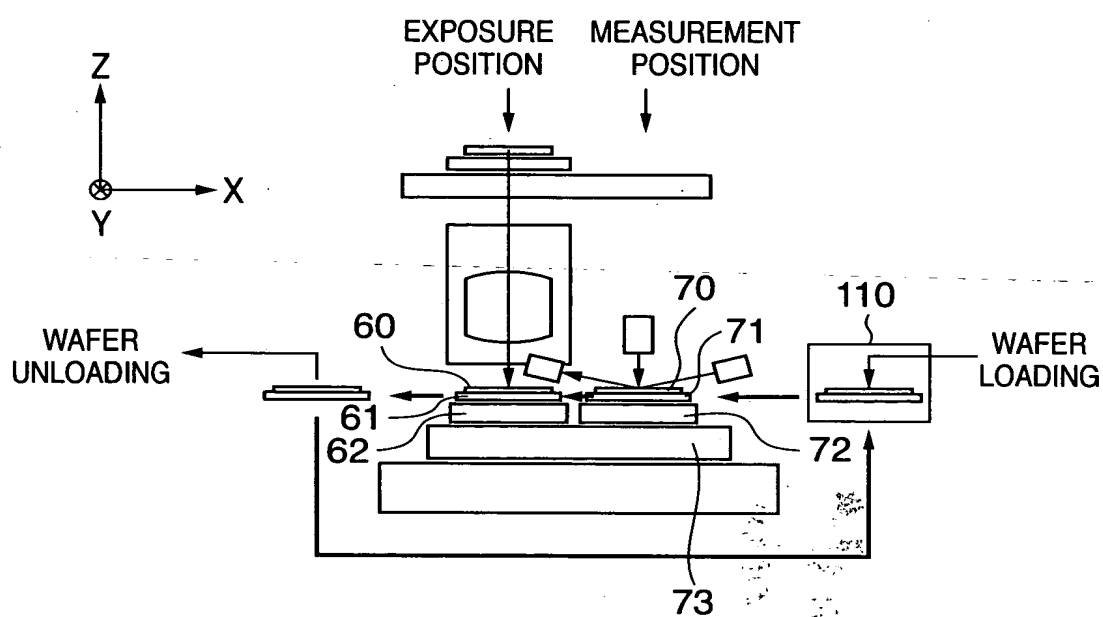
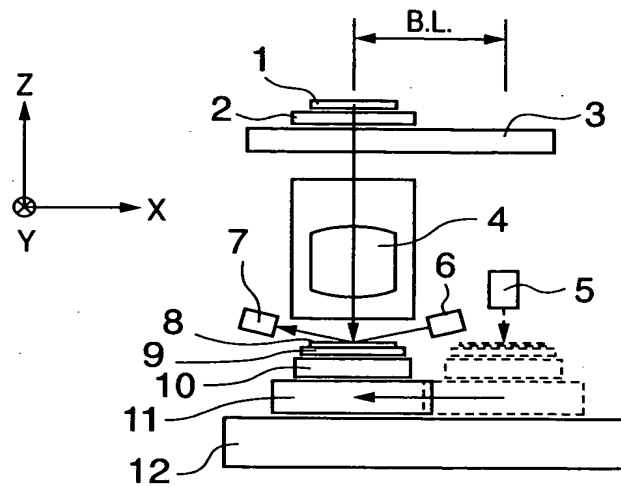
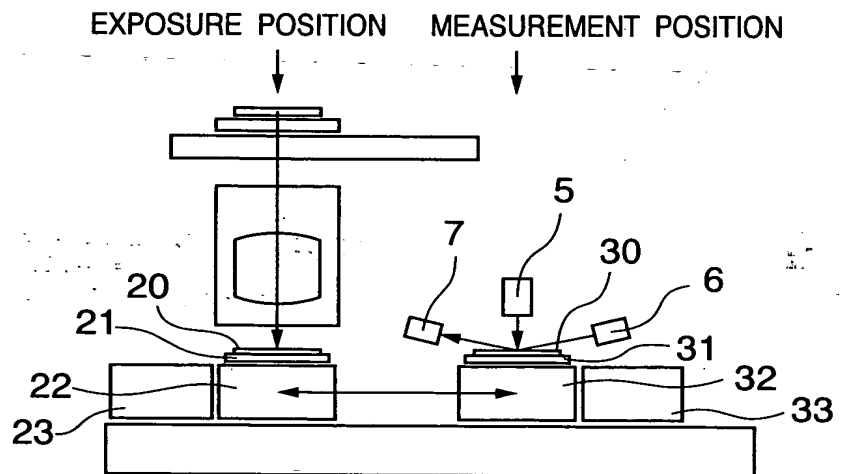
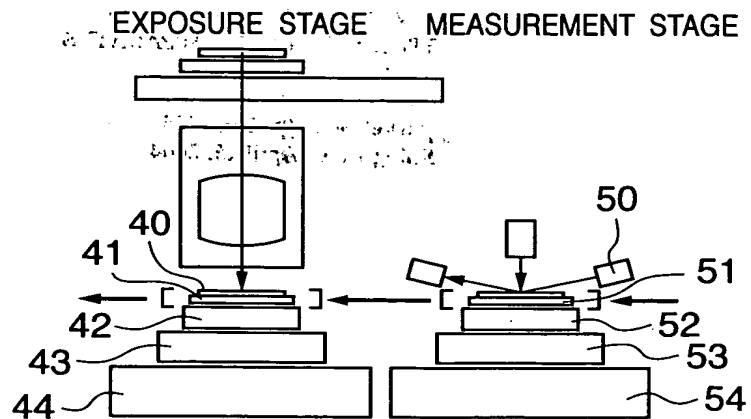
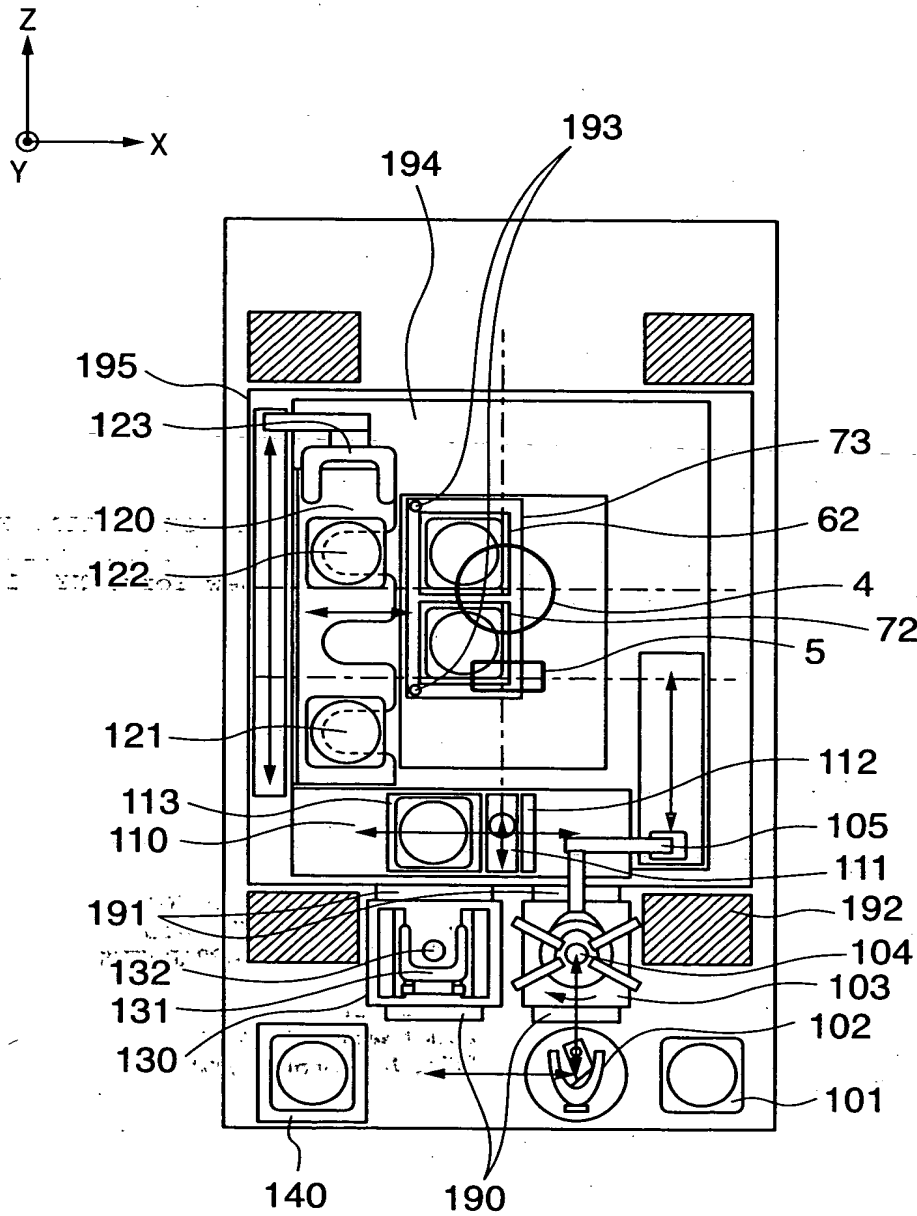
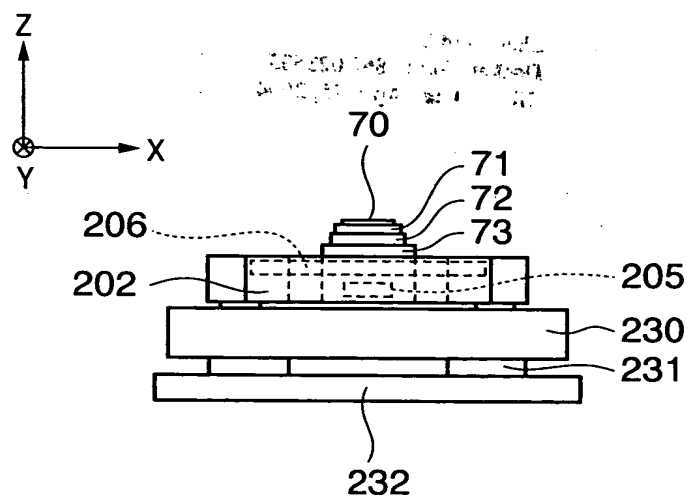


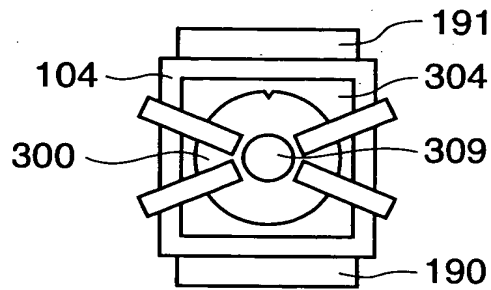
**FIG. 1**

**FIG. 2A****FIG. 2B****FIG. 2C**

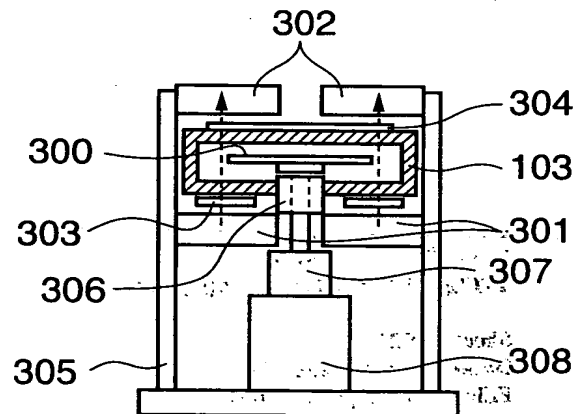
**FIG. 3**

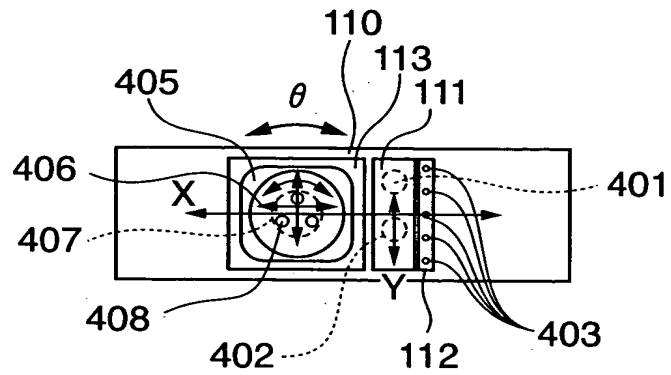
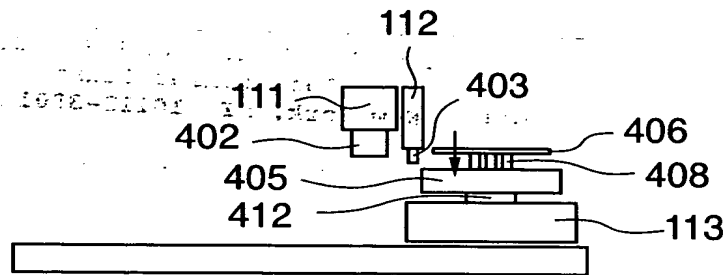
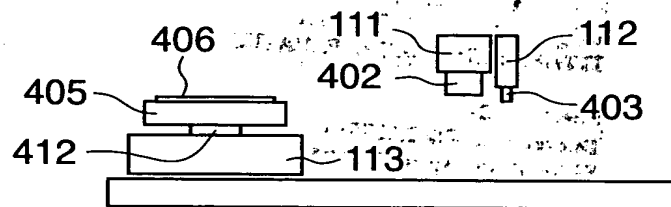
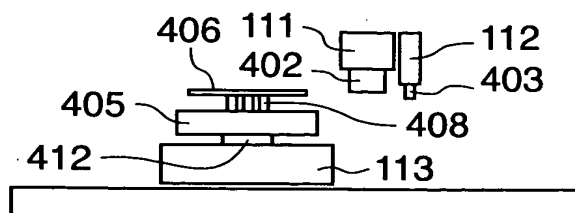


**FIG. 5A**

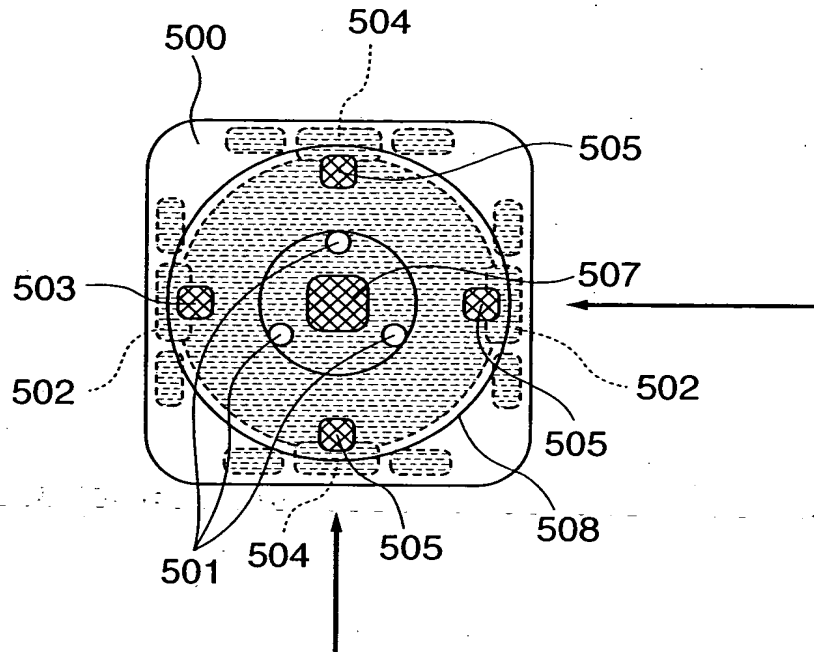


**FIG. 5B**

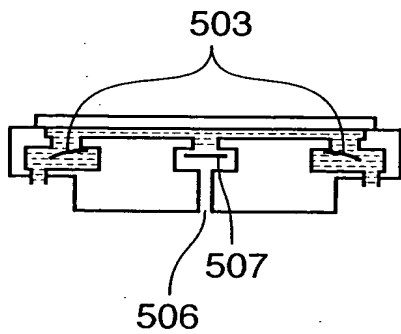


**FIG. 6A****FIG. 6B****FIG. 6C****FIG. 6D**

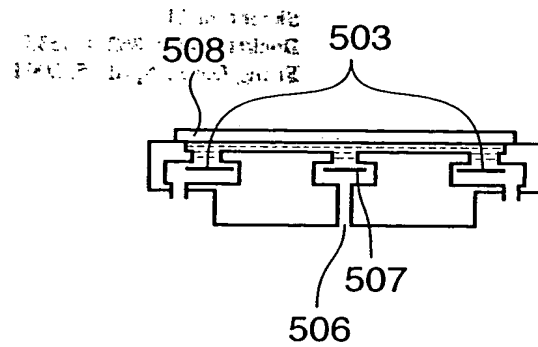
**FIG. 7A**



**FIG. 7B**



**FIG. 7C**



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**FIG. 8A**

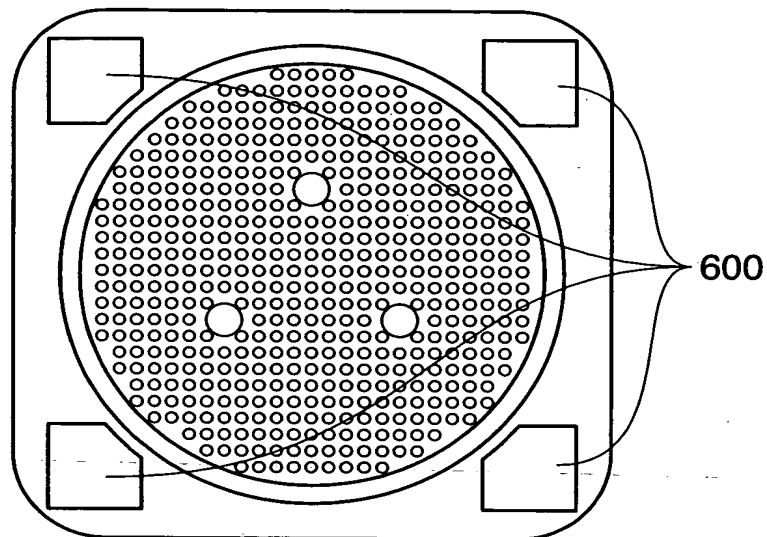
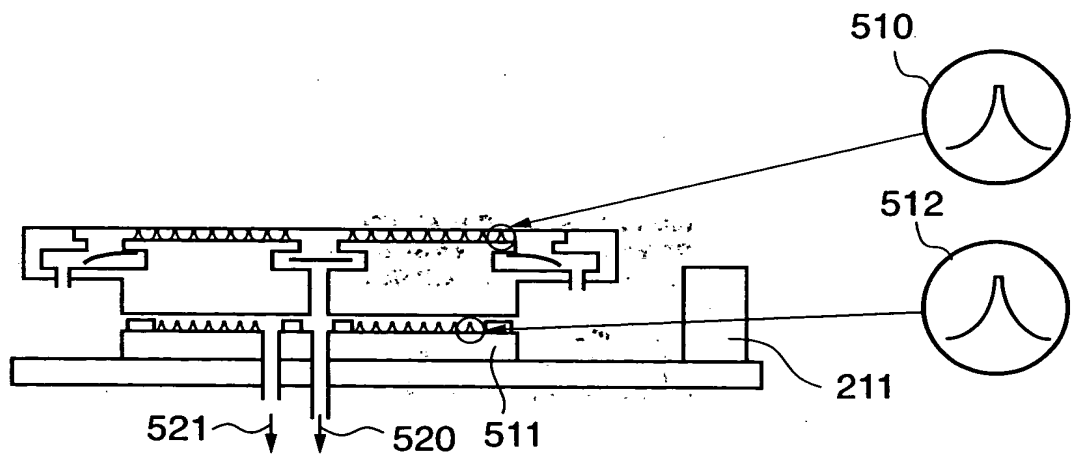


FIG. 8B

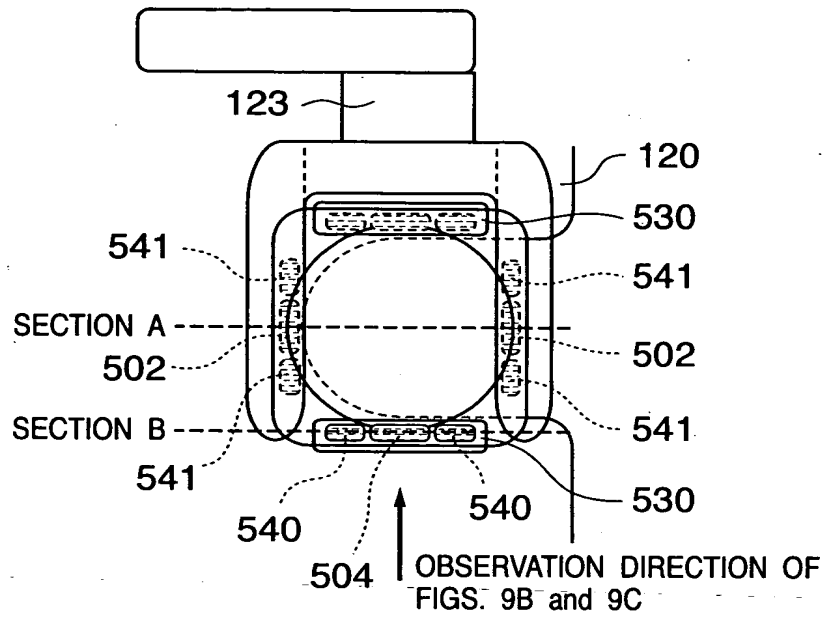
**FIG. 8B**



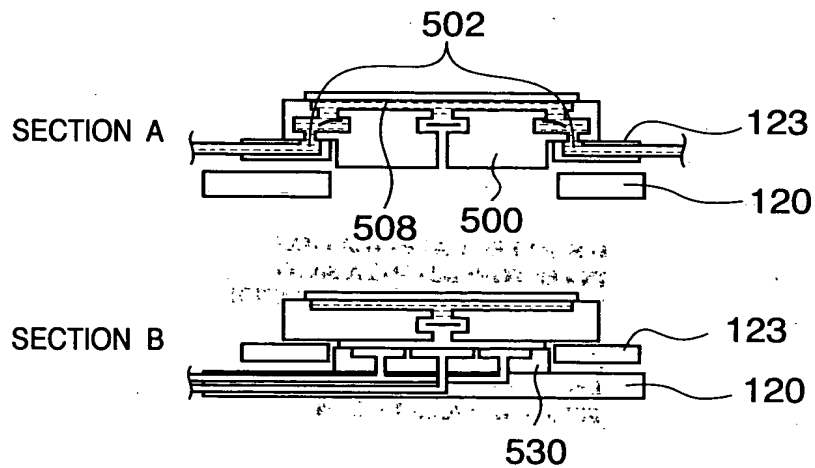


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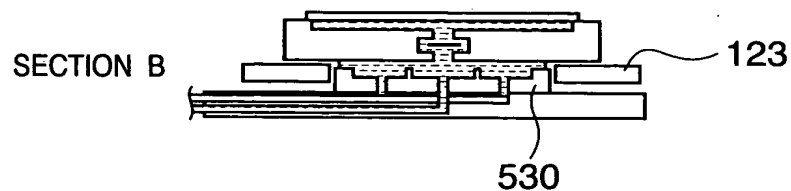
**FIG. 9A**



**FIG. 9B**

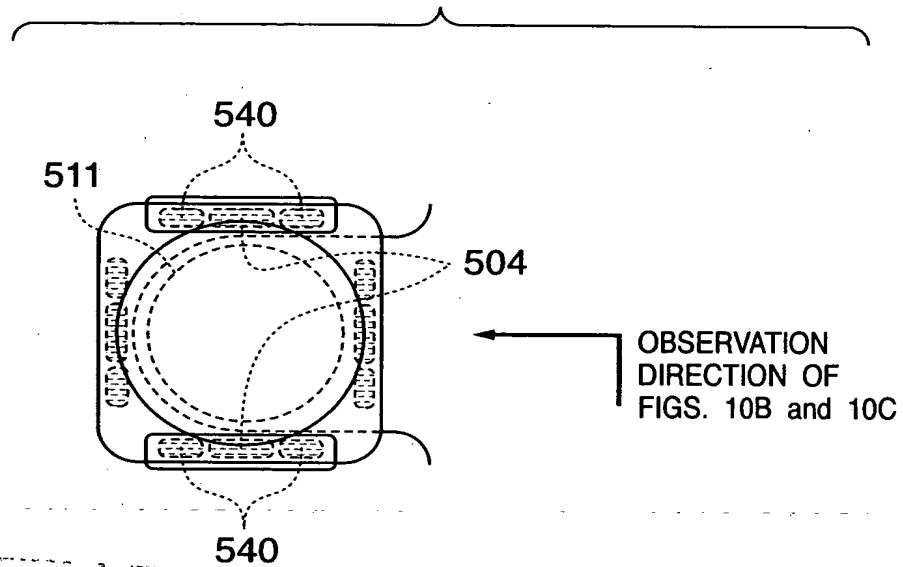


**FIG. 9C**

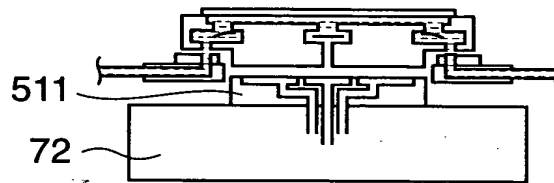


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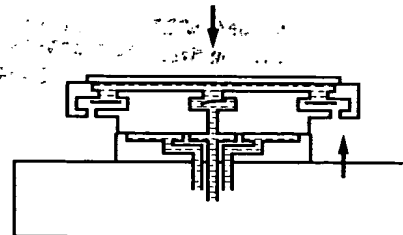
**FIG. 10A**



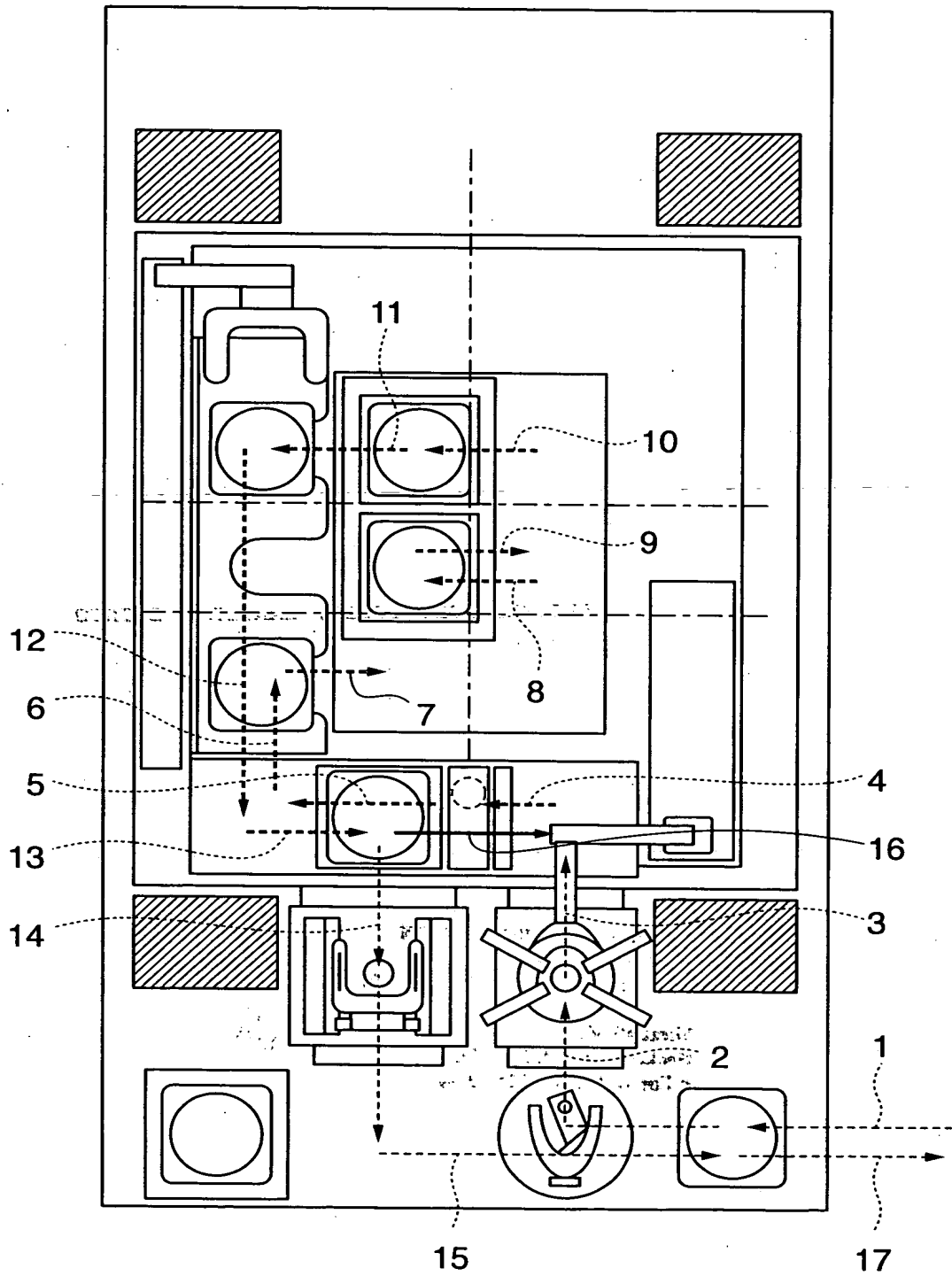
**FIG. 10B**



**FIG. 10C**

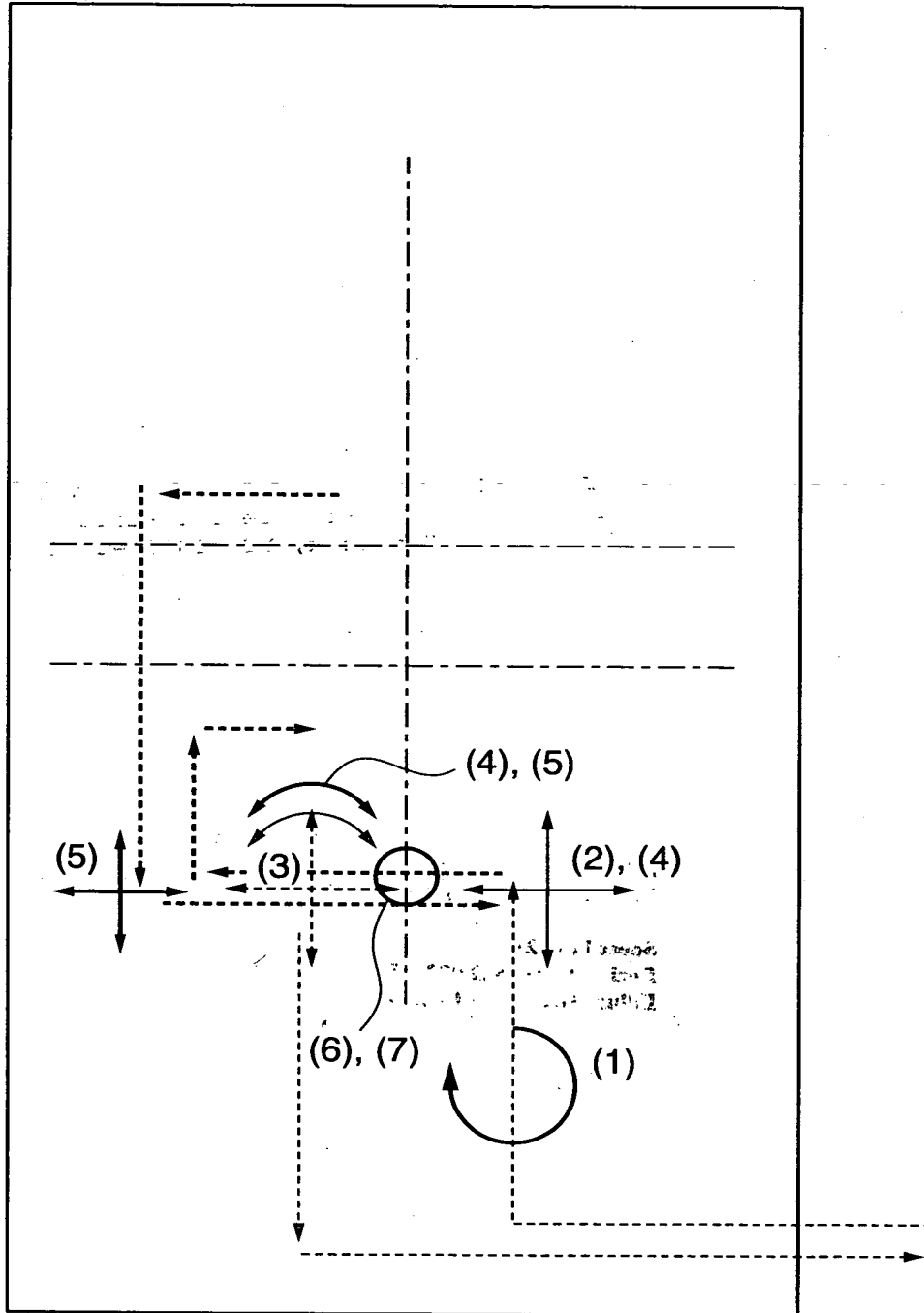


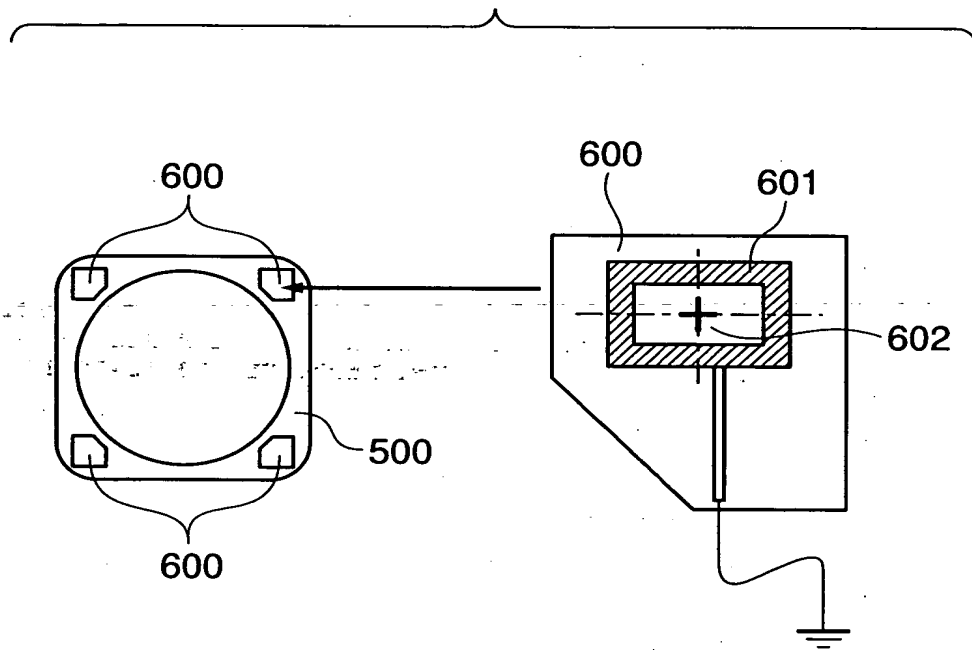
**FIG. 11**

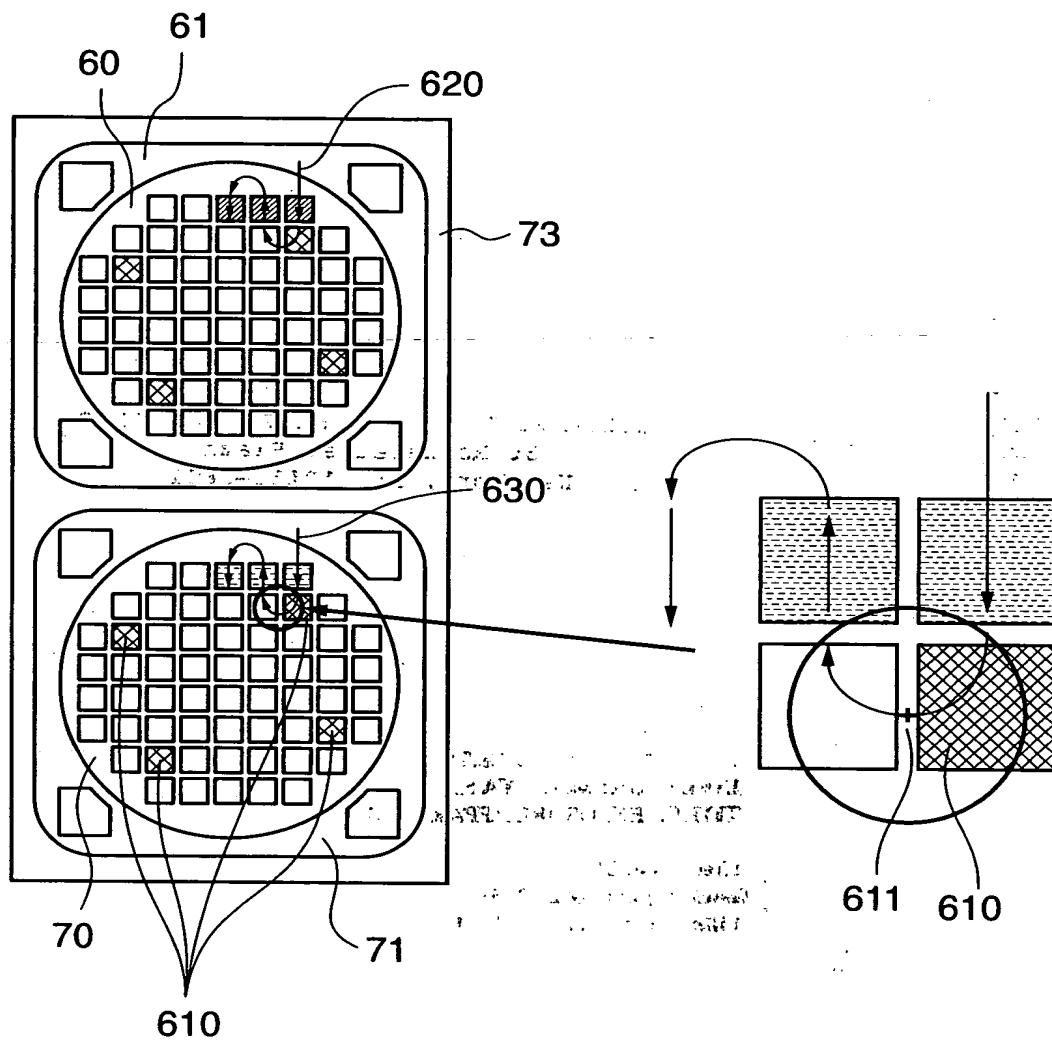


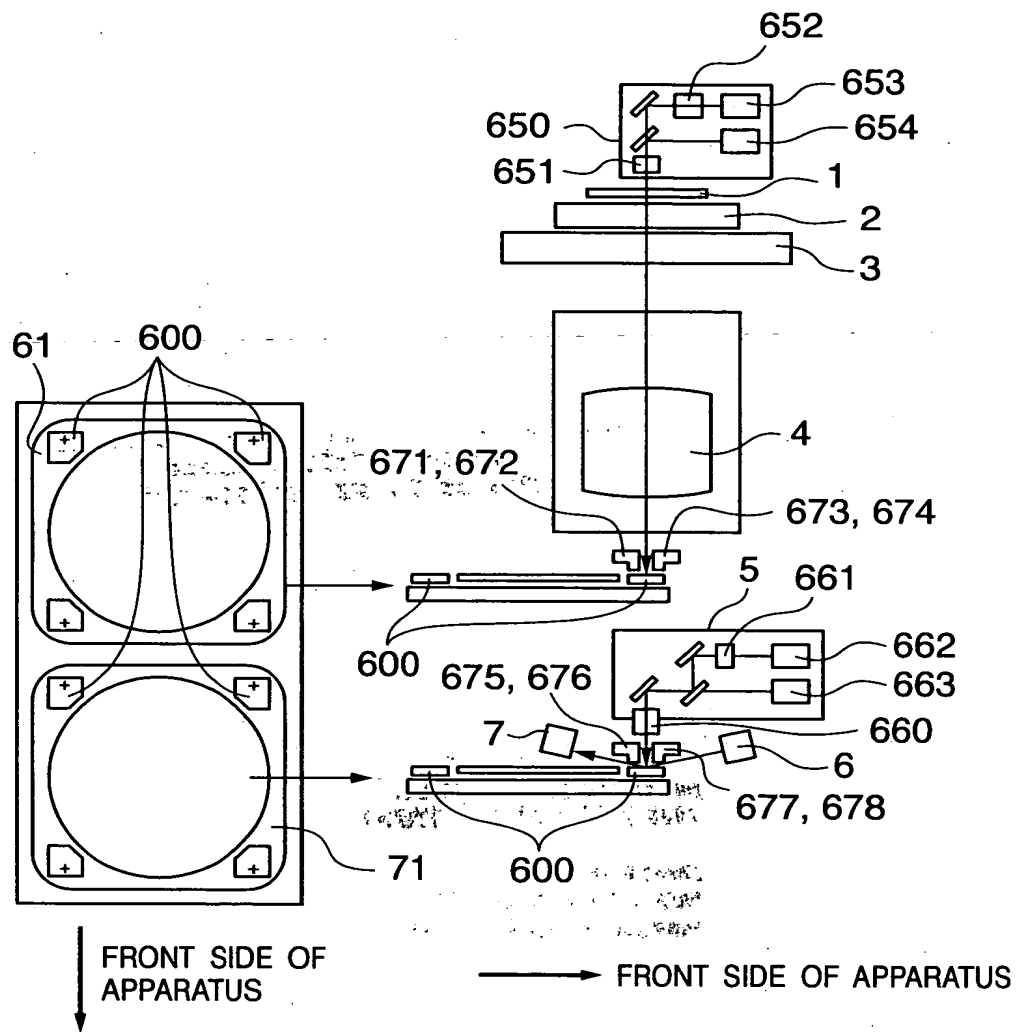
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**FIG. 12**

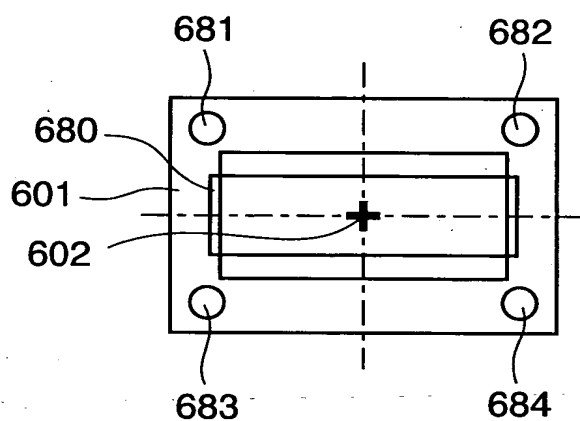


**FIG. 13**

**FIG. 14**

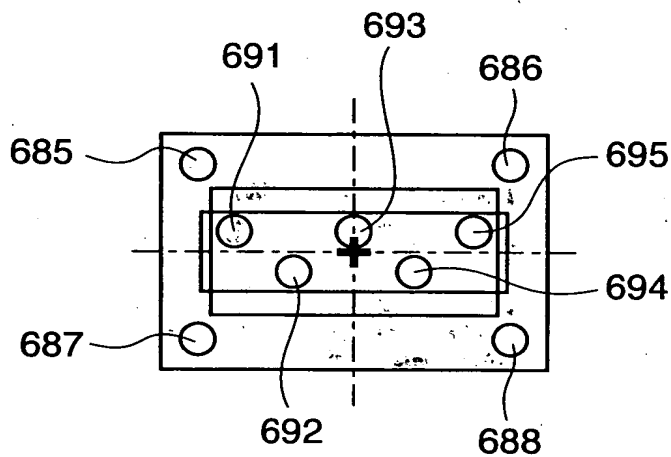
**FIG. 15**

**FIG. 16A**

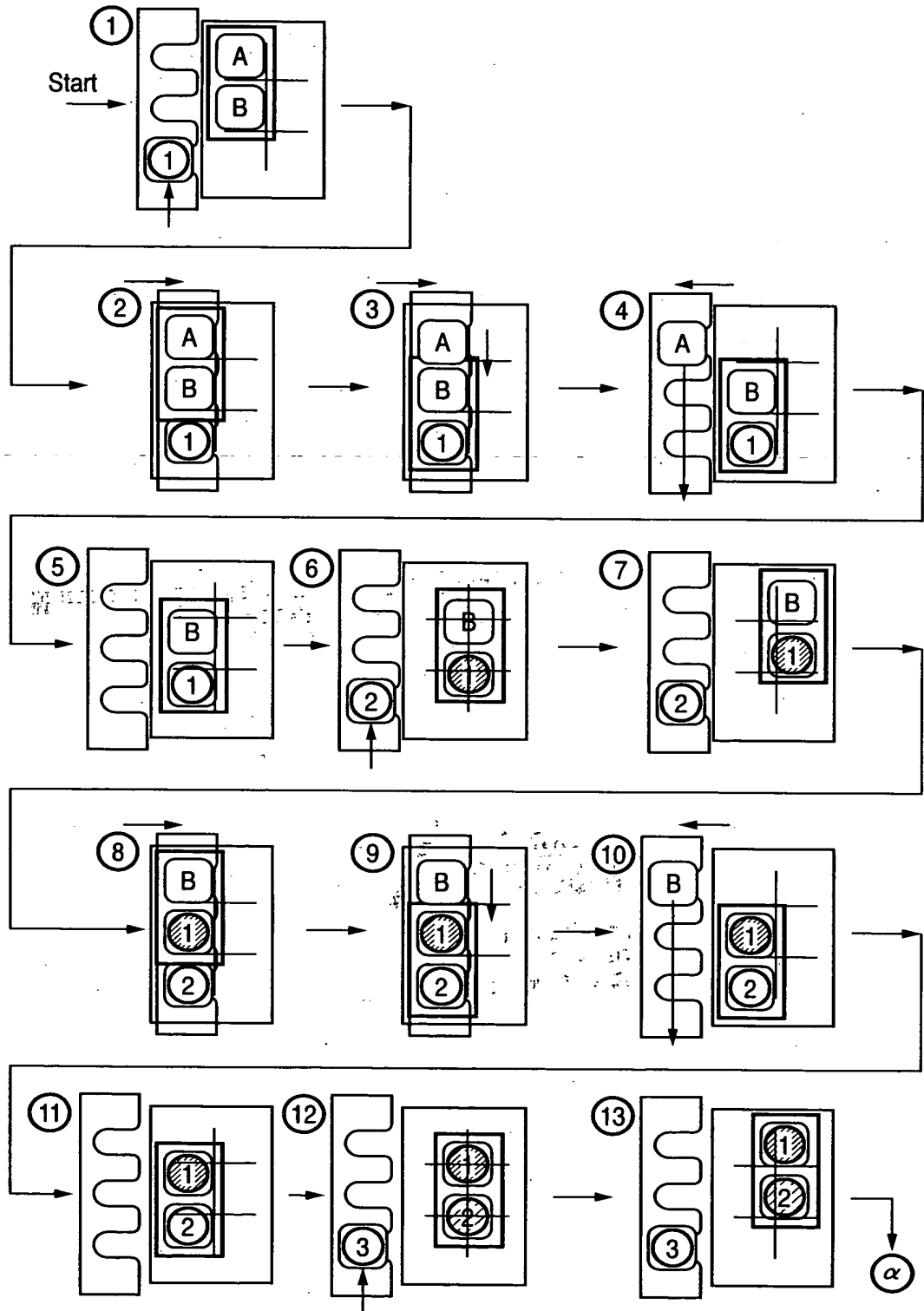


OPTICAL DISPLAY DEVICE, INCLUDING THE  
 METHOD OF MANUFACTURING THE  
 SAME AND THE SYSTEM INCLUDING THE SAME

**FIG. 16B**

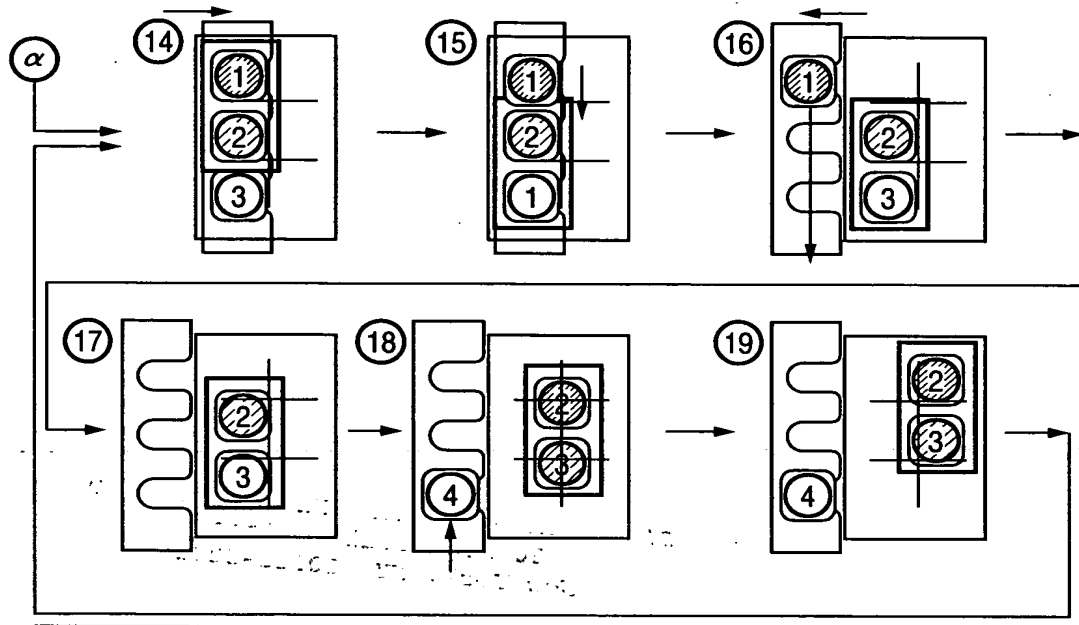




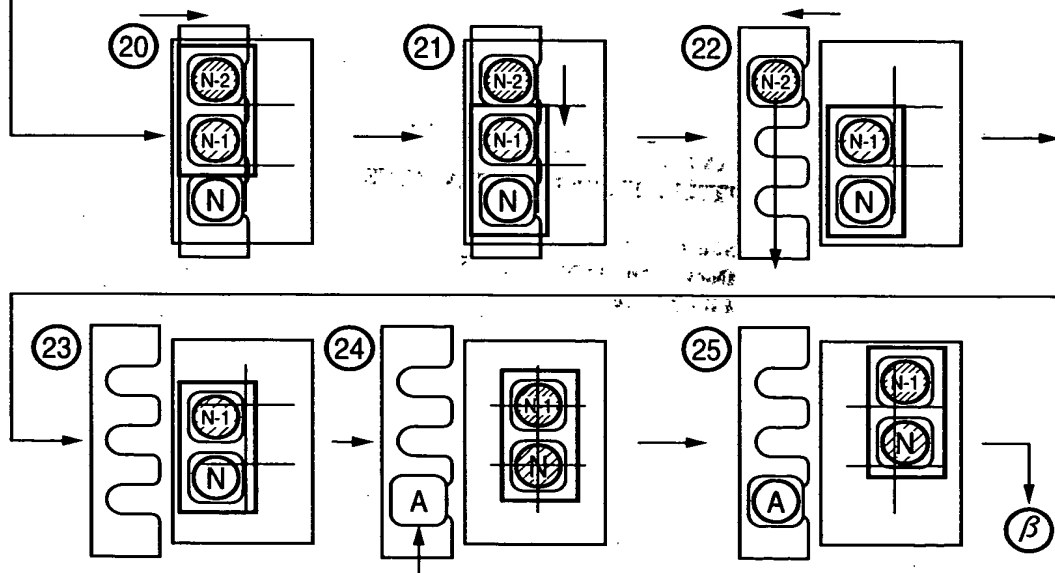
**FIG. 17****1. MEASUREMENT OF FIRST WAFER**

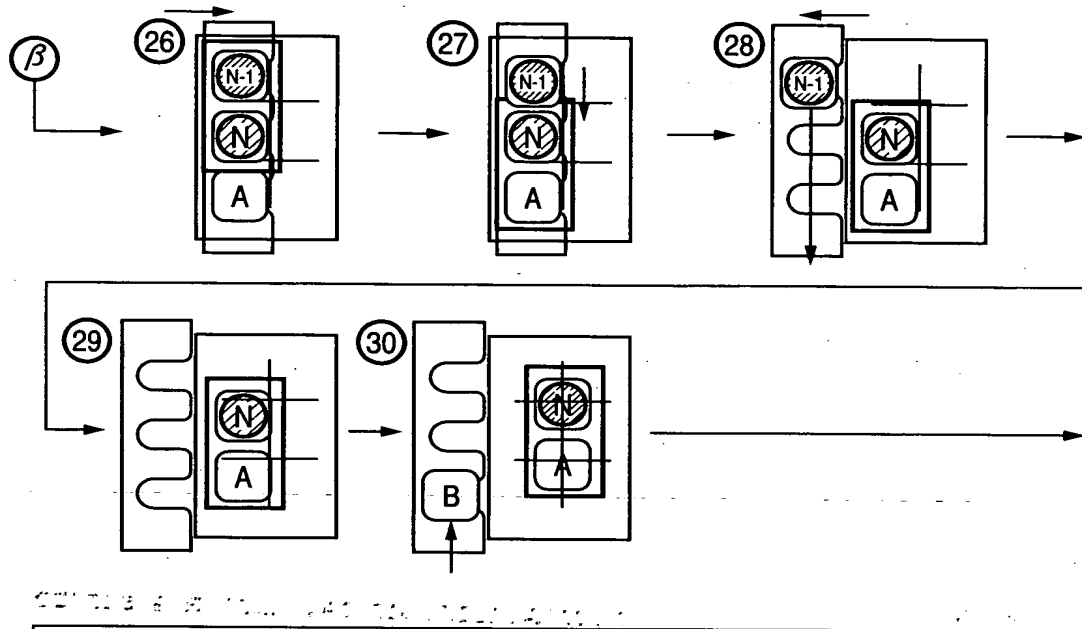
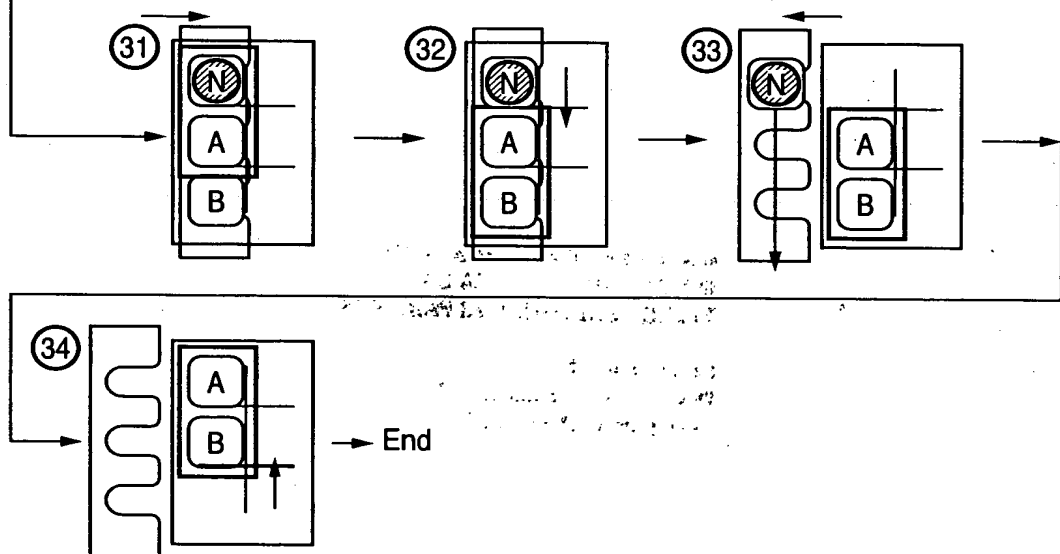
**FIG. 18**

3. (MEASUREMENT OF THIRD TO (N-1)TH WAFERS) &  
(EXPOSURE OF SECOND TO (N-2)TH WAFERS)

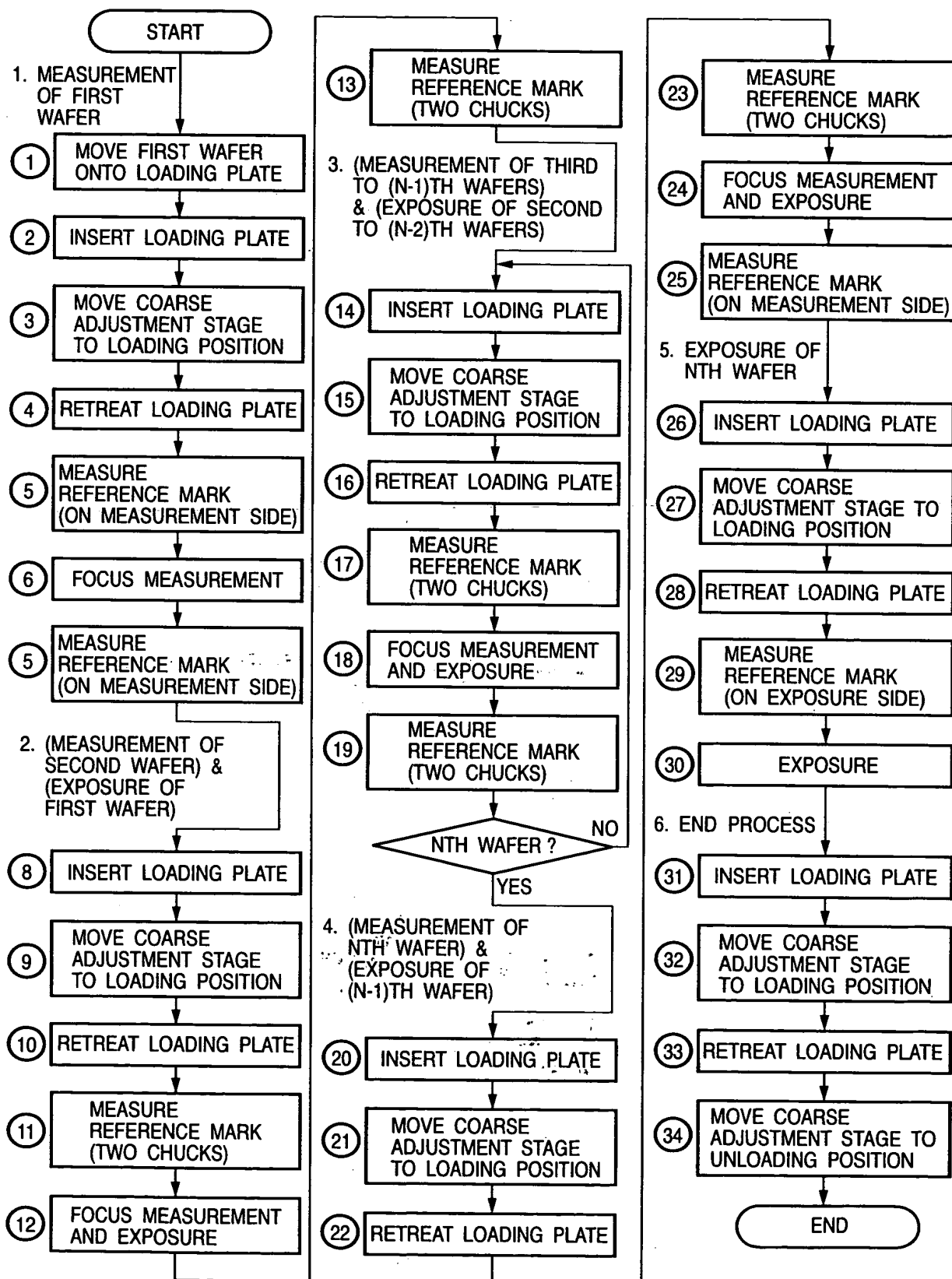


4. (MEASUREMENT OF NTH WAFER) & (EXPOSURE OF (N-1)TH WAFER)



**FIG. 19****5. MEASUREMENT OF NTH WAFER****6. END PROCESS**

## FIG. 20



**FIG. 21**